

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
-30V	11m Ω @-10V	-12A
	17m Ω @-4.5V	

Feature

- TrenchFET Power MOSFET
- Excellent $R_{DS(on)}$ and Low Gate Charge

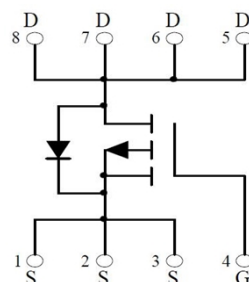
Application

- Advanced trench process technology
- High density cell design for ultra-low on-resistance
- High power and current handling capability
- Ideal for Lion battery pack applications

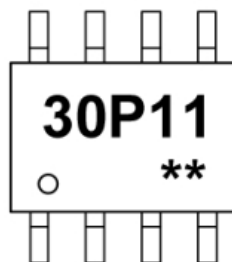
Package



Circuit diagram



Marking



30P11 =Device Code
** =Week Code

Absolute maximum ratings

(T_a=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	-30	V
Gate-Source Voltage	V _{GS}	±25	V
Continuous Drain Current	I _D	-12	A
Pulsed Drain Current ¹⁾	I _{DM}	-55	A
Power Dissipation	P _D	3.2	W
Thermal Resistance from Junction to Ambient ²⁾	R _{θJA}	39	°C/W
Junction Temperature	T _J	150	°C
Storage Temperature	T _{STG}	-55~ +150	°C

Notes:

1. Repetitive rating: Pulse width limited by junction temperature.
2. Surface mounted on FR4 board, t≤10s.

Electrical characteristics

($T_A=25^{\circ}\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV (BR)DSS	V _{GS} = 0V, I _D = -250μA	-30			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -30V, V _{GS} = 0V			-1	uA
Gate-Source Leakage	I _{GSS}	V _{GS} = ±20V, V _{DS} =0V			±100	uA
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D = -250μA	-1.2	-1.8	-2.5	V
Drain-Source On-Resistance ¹	R _{DS(on)}	V _{GS} = -20V, I _D = -12A		9.5	12	mΩ
		V _{GS} = -10V, I _D = -12A		11	14	
		V _{GS} = -6V, I _D = -10A		13	18	
		V _{GS} = -4.5V, I _D = -10A		17	23	
Dynamic Characteristics						
Input Capacitance	C _{iSS}	V _{DS} = -15V, V _{GS} =0V, f=1MHz		2070		pF
Output Capacitance	C _{oSS}			503		
Reverse Transfer Capacitance	C _{rSS}			302		
Switching Characteristics						
Turn-on Delay Time	T _{d(on)}	V _{GS} = -10V, V _{DD} = -15V, R _{GEN} =3Ω, R _L =3Ω		12.4		nS
Turn-on Rise Time	T _r			8.2		
Turn-off Delay Time	T _{d(off)}			25.+		
Turn-off Fall Time	T _f			12		
Total Gate Charge	Q _g	V _{DS} = -15V, I _D = -10A, V _{GS} = -12V		37.4		nC
Gate-Source Charge	Q _{gs}			7		
Gate-Drain Charge	Q _{gd}			10.4		
Drain-Source Diode Characteristics						
Forward on voltage	V _{SD}	I _{SD} = -1A,V _{GS} =0V			-1	V

Note:

1. Repetitive rating: Pulse width limited by junction temperature.
2. Surface mounted on FR4 board, $t \leq 10s$.
3. Pulse Test: Pulse Width $\leq 80\mu s$, Duty Cycle $\leq 0.5\%$.
4. Guaranteed by design, not subject to producing.

Typical Characteristics

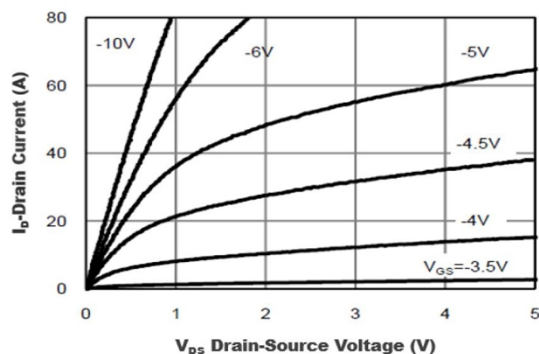


Figure1. Output Characteristics

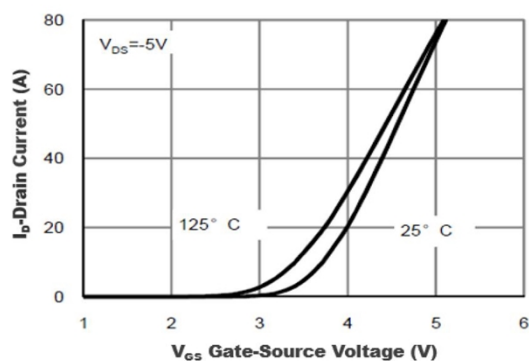


Figure2. Transfer Characteristics

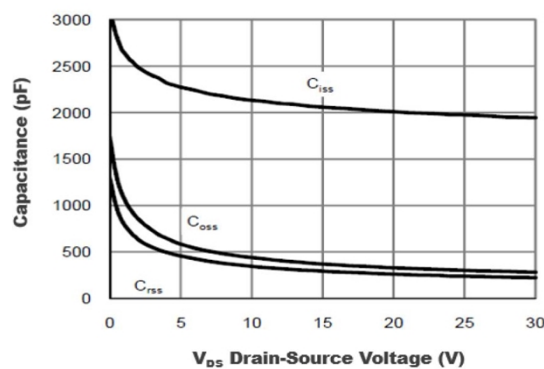


Figure3. Capacitance Characteristics

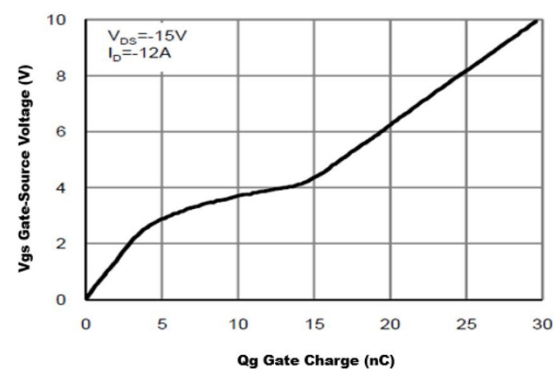


Figure4. Gate Charge

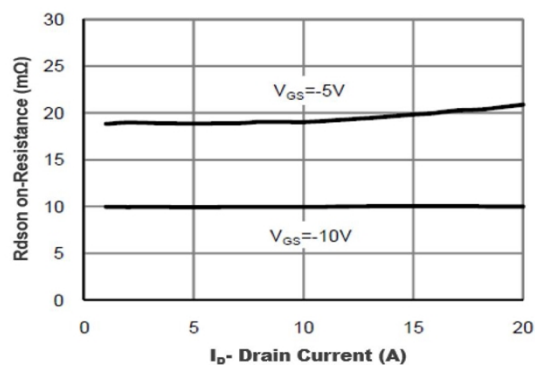


Figure5. Drain-Source on Resistance

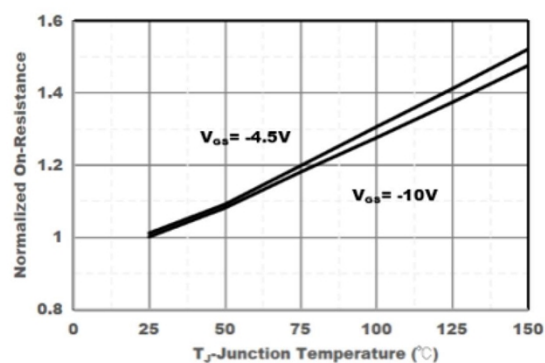


Figure6. Drain-Source on Resistance

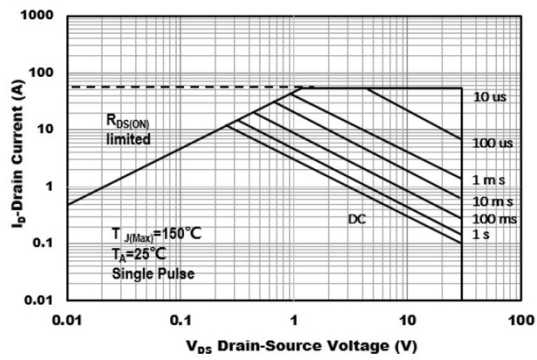


Figure7. Safe Operation Area

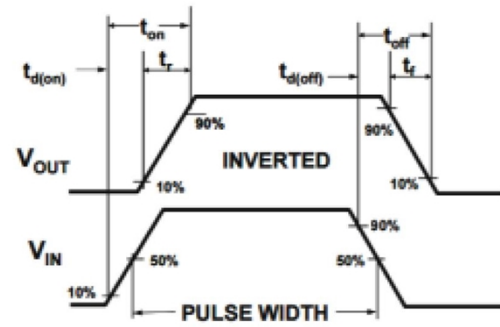
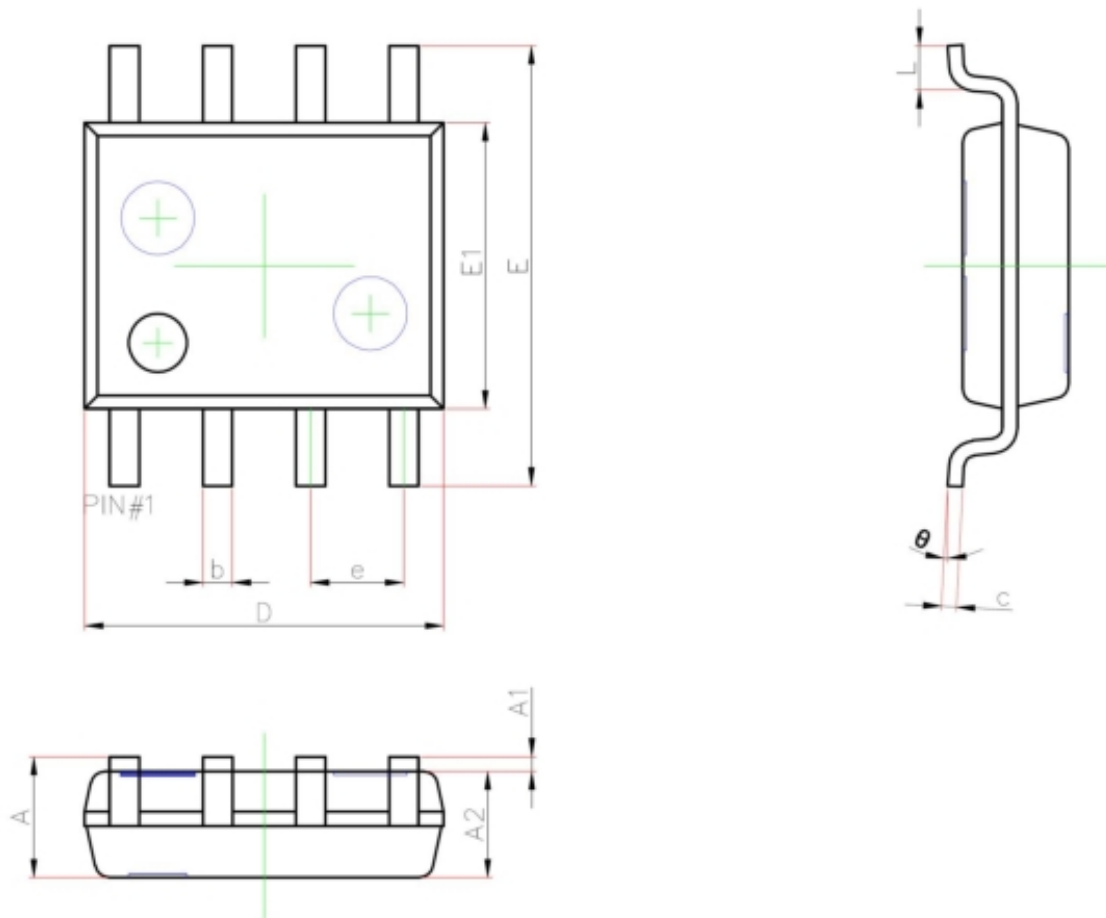


Figure8. Switching wave

SOP-8 Package Information



Symbol	Dimensions In Millimeters	
	Min.	Max.
A	1.35	1.75
A1	0.10	0.25
A2	1.35	1.55
b	0.33	0.51
c	0.17	0.25
D	4.80	5.00
e	1.27 REF.	
E	5.80	6.20
E1	3.80	4.00
L	0.40	1.27
θ	0°	8°